

# STLVDS3487

### High speed differential line drivers

### Feature summary

- Meets or exceeds the requirements of ansi TIA/EIA-644 standard
- Low voltage differential signaling with typical output voltage of 350mV and a 100Ω load
- Typical output voltage rise and fall times of 750ps (400Mbps)
- Typical propagation delay times of 1.7ns
- Operates from a single 3.3V supply
- Power dissipation 25mW typical per driver at 200MHz
- Driver at high impedance when disabled or with V<sub>CC</sub> = 0V
- Pin compatible with the MC3487 and SN65LVD3487
- Low voltage TTL (LVTTL) logic input levels

### Description

The STLVDS3487 is a quad differential line drivers that implements the electrical characteristics of low voltage differential signaling (LVDS). This signaling technique lowers the output voltage levels of 5V differential standard levels (such as TIA/EIA-4225) to reduce the power, increase the symphonizing speeds and allows



operations with a 3.3V supply fail. Any of the four current mode drivers will deliver a minimum differential output voice ge magnitude of 247mV into a 100 $\Omega$  load when enabled.

The intended application of this device and signalling to chinque is for point-to-point baseband data transmission over controlled impedance media approximately  $100\Omega$ . The transmission nuedia may be printed circuit board traces, backplanes or cables. The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media and noise coupling to the environment.

The STLVDS3487 is characterized for operation from -40°C to 85°C.

### Order code

Part number	Temperature Range	Package	Comments
STLVDS3487BTR	-40 to 85 °C	TSSOP16 (Tape & Reel)	2500 parts per reel
April 2006		Rev. 2	1/16

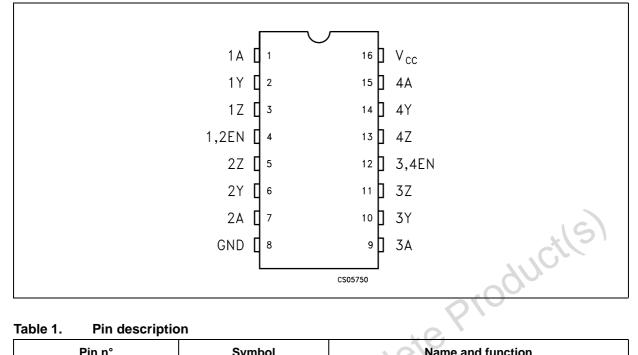
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#### **Pin configuration** 1

Figure 1	۱.	Pin	connections
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#### **Pin description** Table 1.

Table 1. Pin description	on	
Pin n°	Symbol	Name and function
1, 7, 9, 15	1A to 4A	Driver inputs
2, 6, 10, 14	1Y to 4Y	Driver outputs
3, 5, 11, 13	1Z to 4Z	Driver outputs
4	1EN, 2EN	Drivers 1 and 2 enable
12	3EN, 4EN	Drivers 3 and 4 enable
8	GND	Ground
16	V <sub>cc</sub>	Supply voltage

Table 2. Truth table			
Input	Enables	Out	puts
SO'A	EN	Y	Z
н	Н	Н	L
L	Н	L	Н
Х	L	Z	Z
OPEN	Н	L	Н

L=Low level, H=High Level, X=Don't care, Z= High Impedance



## 2 Logic diagram

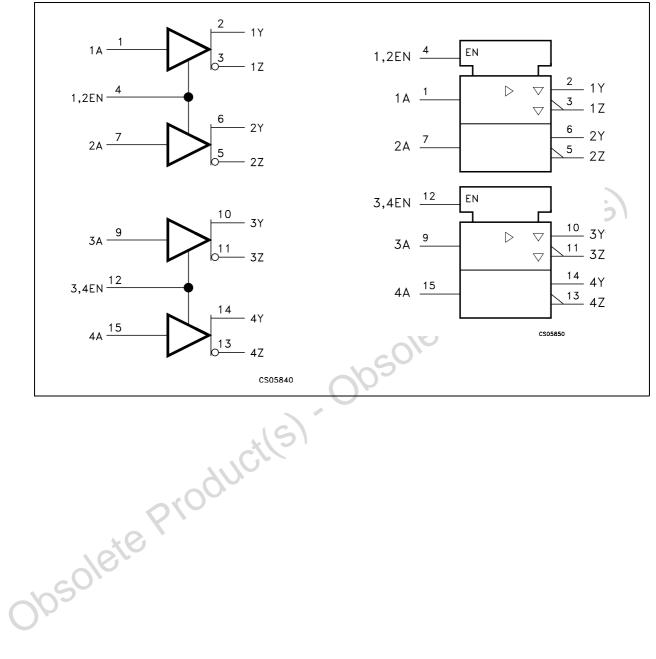


Figure 2. Logic diagram and logic symbol

## 3 Maximum ratings

Table 3.	Absolute maximum ratings
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Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Supply voltage (Note 1)	-0.5 to 4.6	V
VI	DC Input voltage	-0.5 to (V <sub>CC</sub> + 0.5)	V
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C

Note: Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied.

Note: 1 All voltages except differential I/O bus voltage, are with respect to the network ground terminal.

Parameter	Min.	Тур.	Max.	Uni
Supply voltage	3	3.3	3.6	V
High level input voltage	2	~(O)	J.	V
Low level input voltage		K,	0.8	V
Operating temperature range	-40		85	°C
oroductles				
stepti				
-	High level input voltage     Low level input voltage     Operating temperature range	High level input voltage 2   Low level input voltage -40	High level input voltage 2   Low level input voltage -40	High level input voltage 2   Low level input voltage 0.8   Operating temperature range -40 85

Table 4. Recommended operating conditions

## 4 Electrical characteristics

#### Table 5. Electrical characteristics

(Over recommended operating conditions unless otherwise noted. All typical values are at  $T_A$  = 25°C, and  $V_{CC}$  = 3.3V).

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Uı
V <sub>OD</sub>	Differential output voltage		247	350	454	m
$\Delta V_{OD}$	Change in differential output voltage between logic state	R <sub>L</sub> = 100Ω, Fig. 2	-50		50	m
$\Delta V_{OC(SS)}$	Change in steady-state common mode output voltage between logic state	Fig. 3	1.125	1.2	1.375	``
V <sub>OC(SS)</sub>	Steady-state common mode output voltage	Fig. 3	-50		50	m
V <sub>OC(PP)</sub>	Peak to peak common mode output voltage			80	150	'n
		V <sub>IN</sub> = 0.8V or 2V, Enabled, No Load		11.5	20	r
I <sub>CC</sub>	Supply current	$V_{IN}$ = 0.8V or 2V, Enabled, R <sub>L</sub> =100 $\Omega$		25	35	r
		$V_{IN} = 0$ or $V_{CC}$ , Disabled		0.3	1	n
I <sub>IH</sub>	High level input current	V <sub>IH</sub> = 2V		4	20	μ
۱ <sub>IL</sub>	Low level input current	V <sub>IL</sub> = 0.8V		0.6	10	h
laa	Short circuit output current	$V_{O(Y)}$ or $V_{O(Z)} = 0V$		6.1	-24	n
I <sub>SC</sub>	Short circuit output current	$V_{OD} = 0$			± 12	n
I <sub>OZ</sub>	High impedance output current	$V_{O} = 0 \text{ or } 2.4 V$			± 1	μ
I <sub>OFF</sub>	Power OFF output current	$V_{CC} = 0V_O = 2.4V$			± 1	μ
C <sub>IN</sub>	Input capacitance	DI		3		p
	Input capacitance					



#### Table 6.Switching characteristics

(Over recommended operating conditions unless otherwise noted. All typical values are at  $T_A = 25$ °C, and  $V_{CC} = 3.3$ V).

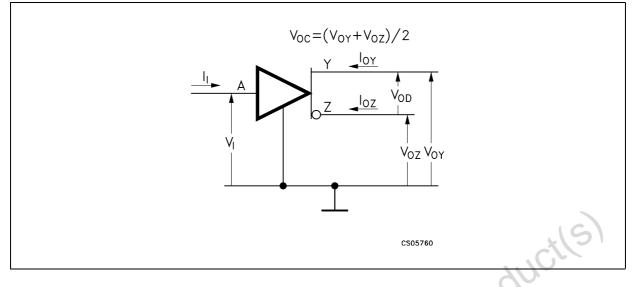
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>PLH</sub>	Propagation Delay Time, Low to High Output		0.5	1.4	2	ns
t <sub>PHL</sub>	Propagation Delay Time, High to Low Output		1	1.7	2.5	ns
t <sub>r</sub>	Differential Output Signal Rise Time	$R_L = 100\Omega, C_L = 10pF$	0.4	0.5	0.6	ns
t <sub>f</sub>	Differential Output Signal Fall Time	Fig. 2	0.4	0.5	0.6	ns
t <sub>sk(P)</sub>	Pulse Skew ( t <sub>THL</sub> = t <sub>TLH</sub>  )			0.3	0.6	ns
t <sub>sk(O)</sub>	Channel to Channel Output Skew (note1)			0	0.3	ns
t <sub>PZH</sub>	Propagation Delay Time, High Impedance to High Level Output			5.4	15	ns
t <sub>PZL</sub>	Propagation Delay Time, High Impedance to Low Level Output			2.5	15	ns
t <sub>PHZ</sub>	Propagation Delay Time, High Level to High Impedance Output	Fig. 4	6(	8.1	15	ns
t <sub>PLZ</sub>	Propagation Delay Time, Low Level to High Impedance Output	-lete		7.3	15	ns

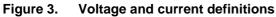
Note: 1  $t_{sk(O)}$  is the maximum delay time difference between drivers on the same device.

2 RS-232 IN to TTL-CMOS OUT (from 50% to 50%)

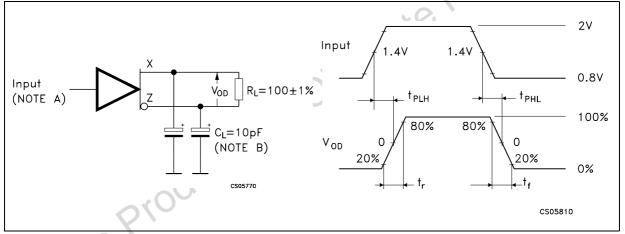
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### 5 Test circuit



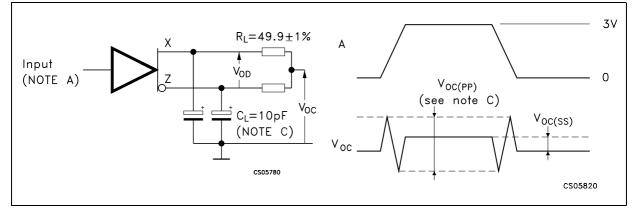






Note A: All input pulse are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 1$ ns, pulse repetition rate (PRR) = 50Mpps, pulse width = 10 ± 0.2ns.

Note B: C<sub>L</sub> includes instrumentation and fixture capacitance within 6mm of the D.U.T



#### Figure 5. Test circuit and definitions for the driver common mode output voltage

Note A: All input pulse are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 1$ ns, pulse repetition rate (PRR) = 50Mpps, pulse width = 10 ± 0.2ns.

Note B: C<sub>L</sub> includes instrumentation and fixture capacitance within 6mm of the D.U.T Note C: The measurement of V<sub>OC(PP)</sub> is made on test equipment with a -3dB bandwidth of at least 300MHz.



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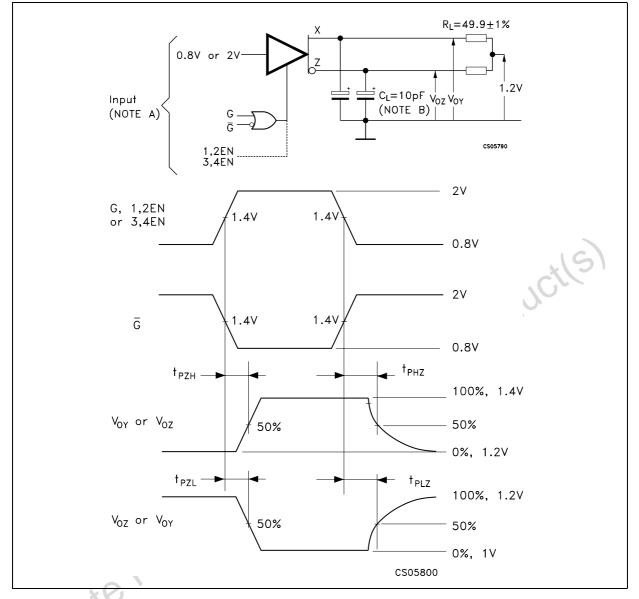
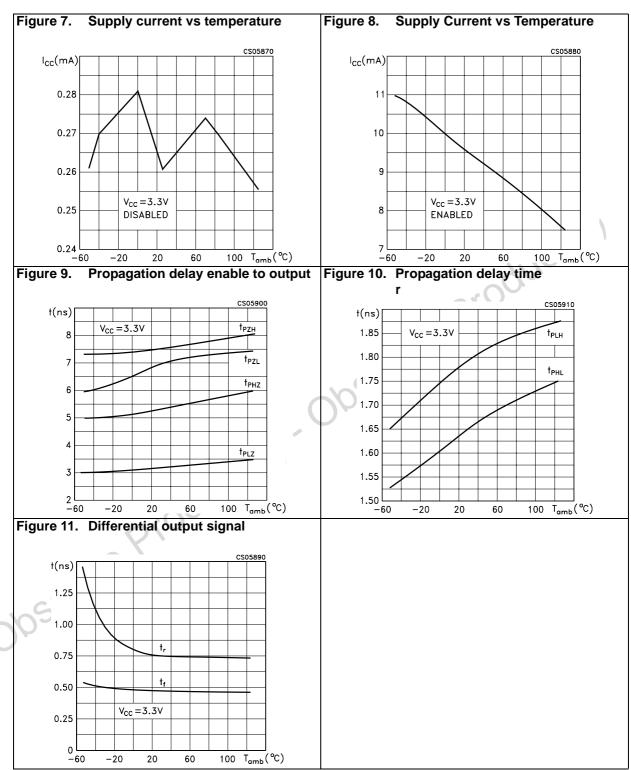


Figure 6. Enable and disable time test circuit and waveform

Note A: All input pulse are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5Mpps, pulse width = 500 ± 10ms.

Note B: C<sub>L</sub> includes instrumentation and fixture capacitance within 6mm of the D.U.T

## 6 Typical performance characteristics



(unless otherwise specified at  $T_J = 25^{\circ}C$ )



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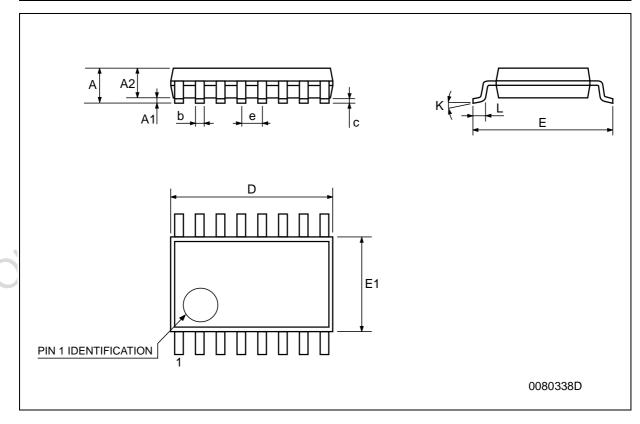
## 7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK<sup>®</sup> packages. These packages have a Lead-free second level interconnect. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

obsolete Product(s) - Obsolete Product(s)



DIM	mm.			inch			
DIM.	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.	
А			1.2			0.047	
A1	0.05		0.15	0.002	0.004	0.006	
A2	0.8	1	1.05	0.031	0.039	0.041	
b	0.19		0.30	0.007		0.012	
С	0.09		0.20	0.004		0.0079	
D	4.9	5	5.1	0.193	0.197	0.201	
Е	6.2	6.4	6.6	0.244	0.252	0.260	
E1	4.3	4.4	4.48	0.169	0.173	0.176	
е		0.65 BSC			0.0256 BSC		
К	0°		8°	0°		8°	
L	0.45	0.60	0.75	0.018	0.024	0.030	

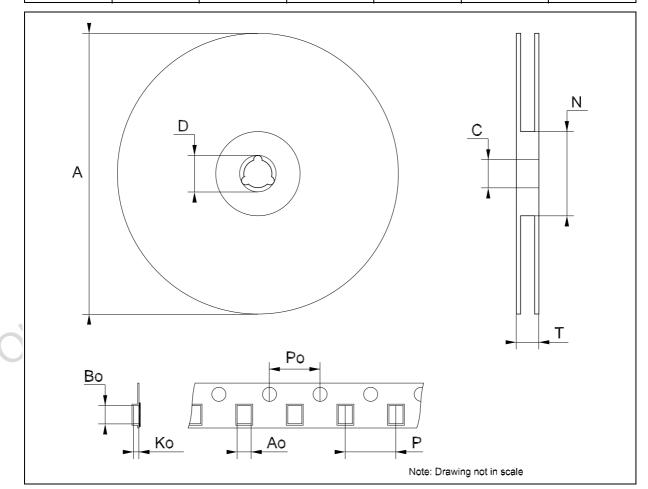


### **TSSOP16 MECHANICAL DATA**

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DIM.		mm.		inch			
	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.	
А			330			12.992	
С	12.8		13.2	0.504		0.519	
D	20.2			0.795			
N	60			2.362			
Т			22.4			0.882	
Ao	6.7		6.9	0.264		0.272	
Во	5.3		5.5	0.209		0.217	
Ko	1.6		1.8	0.063		0.071	
Po	3.9		4.1	0.153		0.161	
Р	7.9		8.1	0.311		0.319	





## 8 Revision history

#### Table 7.Revision history

Date	Revision	Changes
06-Apr-2006	2	Order codes has been updated and new template.

obsolete Product(s). Obsolete Product(s)

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